



Linktel is participating in OIF Co-packaging demo and CEI demo with our ELSFP and 800G LPO products.

- The External Laser Small Form-Factor Pluggable (ELSFP) is a faceplate pluggable form factor to address the laser packaging requirements for co-packaged optical (CPO) systems with optical engines (OEs) which do not have integrated lasers, but rather choose to locate lasers external to the OE.

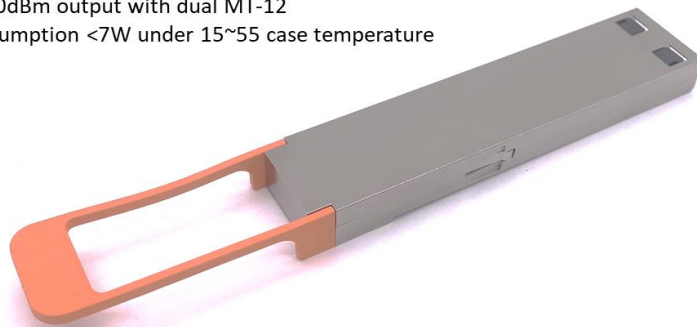
ELSFP-VHP

Characteristic:

Compliance with IA OIF-ELSFP-01.0

8 channels 20dBm output with dual MT-12

Module consumption <7W under 15~55 case temperature



- 800G LPOs are designed without DSPs or CDRs, resulting in significantly lower power consumption and dramatically reduce latency compared to conventional DSP based solutions. The reduction in latency has become a key driver for the growing demand for LPOs in applications such as switch-to-switch, switch-to-server, and GPU-to-GPU connectivity in Machine Learning and High-Performance Computing. Linktel's LPO portfolio consists of modules for both multimode(SR8) and singlemode(2DR4) applications

800G QSFP-DD LPO 2DR4

Characteristic:

Module consumption < 9W

BER ~1e-8



800G QSFP-DD LPO SR8

Characteristic:
Module consumption < 4W
BER ~1e-6



Linktel Technologies provides high-quality and cutting-edge products and solutions for high speed optical I/O connectivity, including high speed pluggable transceivers, optical engines, and ODM/JDM services. Linktel Technologies has international operation centers and customer service offices in Malaysia, China, Singapore and USA.

Linktel ECOC2023 booth# is 203-204.